

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-13. (Canceled)

14. (Original) A method of manufacturing a slider of a thin-film magnetic head, the slider comprising: a slider section having a first medium facing surface that faces toward a rotating recording medium and an air inflow end; and an element section having a second medium facing surface that faces toward the recording medium, an air outflow end, and a thin-film magnetic head element, wherein the first medium facing surface has concavities and convexities for controlling the orientation of the slider section while the recording medium is rotating, and the slider section and the element section are bonded to each other such that the air inflow end and the air outflow end are disposed on opposite sides with the first and second medium facing surfaces in between, the method comprising the steps of:

producing the slider section;

producing the element section separately from the slider section; and

bonding the slider section and the element section to each other.

15. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein the step of producing the slider section includes the step of forming a plurality of the first medium facing surfaces corresponding to a plurality of the slider sections for a first wafer, and the step of producing the element section includes the step of forming a plurality of the thin-film magnetic head elements on a second wafer.

16. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein:

the step of producing the slider section includes the steps of: forming a plurality of the first medium facing surfaces corresponding to a plurality of the slider sections for a first wafer

to thereby form a first slider section aggregate including a plurality of the slider sections arranged in a plurality of rows; and cutting the first slider section aggregate to thereby form a second slider section aggregates including a plurality of the slider sections arranged in a row;

the step of producing the element section includes the steps of: forming a plurality of the thin-film magnetic head elements on a second wafer to thereby form a first element section aggregate including a plurality of the element sections arranged in a plurality of rows; and cutting the first element section aggregate to thereby form a second element section aggregate including a plurality of the element sections arranged in a row; and

the step of bonding the slider section and the element section to each other includes the step of bonding the second slider section aggregate and the second element section aggregate to each other to thereby produce a slider aggregate including a plurality of the sliders arranged in a row,

the method further comprising the step of cutting the slider aggregate into a plurality of the sliders separated from one another.

17. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein: the slider section has a substrate portion and a medium facing layer placed on the substrate portion, the element section has an insulating portion surrounding the thin-film magnetic head element, the substrate portion has a hardness greater than that of the insulating portion, the hardness of the medium facing layer is closer to the hardness of the insulating portion as the substrate portion and the medium facing layer are compared in hardness, and

the first medium facing surface is formed on the medium facing layer in the step of producing the slider section.

18. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, further comprising the step of lapping the first and second medium

facing surfaces so as to flatten the first and second surfaces, after the step of bonding the slider section and the element section to each other.

19. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, further comprising, after the step of bonding the slider section and the element section to each other, the step of lapping the first medium facing surface so as to allow the first medium facing surface to have a first surface closer to the element section, a second surface closer to the air inflow end, and a border portion located between the first and second surfaces, and to allow the second surface to slant against the first surface such that the first and second surfaces make a convex shape bent at the border portion.

20. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 19, wherein the first surface and the second surface form an angle of 30° or smaller.

21. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 19, further comprising the step of forming a recess in a region including the border portion in the first medium facing surface.

22. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 19, wherein the second medium facing surface is disposed farther from the recording medium than the first surface of the first medium facing surface is.

23. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein the slider section and the element section are bonded to each other using a ceramic-based adhesive in the step of bonding the slider section and the element section to each other.

24. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein, in the step of bonding the slider section and the element section to each other, a thermosetting adhesive is put between the slider section and the

element section, and the adhesive is cured by heating at a temperature of 300°C or less to thereby bond the slider section and the element section to each other.

25. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein the step of producing the element section includes the steps of: forming a plurality of the thin-film magnetic head elements on one of surfaces of a wafer; and removing at least part of the wafer by lapping the other one of the surfaces of the wafer.

26. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 25, wherein, in the step of bonding the slider section and the element section to each other, a surface formed at the element section by the lapping is bonded to the slider section.

27. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 25, wherein, in the step of bonding the slider section and the element section to each other, a surface opposite to the surface formed at the element section by the lapping is bonded to the slider section.

28. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 25, wherein, in the step of removing at least part of the wafer, the other one of the surfaces of the wafer is lapped with a support plate placed on a plurality of the thin-film magnetic head elements.

29. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 28, wherein at least part of the support plate, the part including the surface facing the thin-film magnetic head elements, has conductivity.

30. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein the step of producing the slider section includes the steps of: forming an etching mask of metal on one of surfaces of a ceramic substrate; and etching the

ceramic substrate by dry etching through the use of the etching mask to thereby form the concavities and convexities on the one of the surfaces of the ceramic substrate.

31. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 30, wherein the dry etching is reactive ion etching.

32. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein the step of producing the slider section includes the steps of: forming a first etching mask of metal on one of surfaces of a ceramic substrate; etching the ceramic substrate by dry etching through the use of the first etching mask to thereby form a first recess in the one of the surfaces of the ceramic substrate; forming a second etching mask to cover part of the first recess; and etching the ceramic substrate further by dry etching through the use of the second etching mask to thereby form a second recess deeper than the first recess in the one of the surfaces of the ceramic substrate.

33. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein a magnetoresistive element for reproduction and an induction-type electromagnetic transducer for recording are formed in this order on one of surfaces of a wafer in the step of producing the element section, and the slider section and the element section are bonded to each other such that the magnetoresistive element is disposed closer to the slider section than the induction-type electromagnetic transducer in the step of bonding the slider section and the element section to each other.

34. (Original) A method of manufacturing a slider of a thin-film magnetic head according to claim 14, wherein an induction-type electromagnetic transducer for recording and a magnetoresistive element for reproduction are formed in this order on one of surfaces of a wafer in the step of producing the element section, and the slider section and the element section are bonded to each other such that the magnetoresistive element is disposed closer to

the slider section than the induction-type electromagnetic transducer in the step of bonding
the slider section and the element section to each other.